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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Kohji Andoh

Date: October 28, 2005

Serial No.: 10/728,482

Group Art Unit: 2812

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Examiner: Andre C. Stevenson

Notice of Allowance Dated: July 29, 2005

Confirmation No. 2109

For PROCESS FOR PREPARATION OF SEMICONDUCTOR WAFER SURFACE

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450  
Attention: Official Draftsperson

SUBMISSION OF FORMAL DRAWINGS

Sir:

Enclosed herewith please find TWO (2) sheets of replacement drawings containing Figures 1-4 for the above-identified application..

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, Attn: Official Draftsperson, on October 28, 2005:

Respectfully submitted,

Samuel H. Weiner

Name of applicant, assignee or  
Registered Representative

  
Signature

October 28, 2005

Date of Signature

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SHW:fs  
Enclosure